

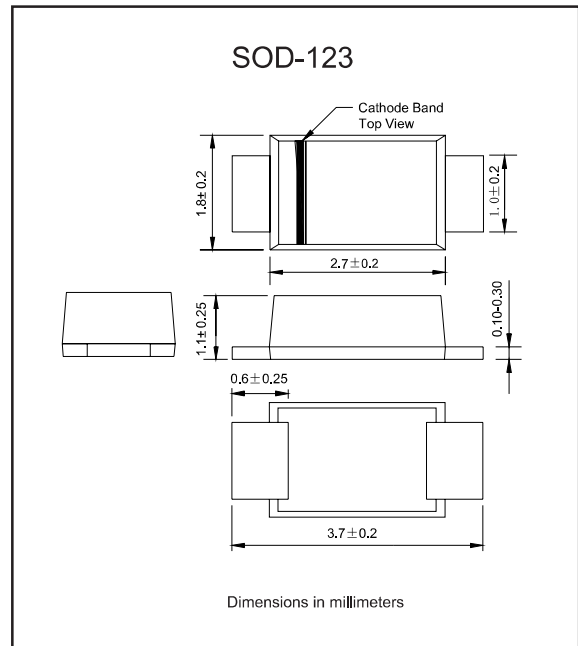
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:  
250°C/10 seconds, 0.375" (9.5mm) lead length, 5 lbs. (2.3kg) tension
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

### Mechanical data

- ◆ **Case:** JEDEC SOD-123 molded plastic body
- ◆ **Terminals:** Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS		Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1		$I_O$			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC method)		$I_{FSM}$			25	A
Reverse current	$T_A = 25^\circ\text{C}$	$V_R = 20\text{V} - 60\text{V}$	$I_R$			0.5	mA
		$V_R = 80\text{V} - 200\text{V}$				0.1	
Reverse current	$T_A = 100^\circ\text{C}$	$V_R = 20\text{V} - 60\text{V}$	$I_R$			10	mA
		$V_R = 80\text{V} - 200\text{V}$				5	
Thermal resistance	Junction to ambient NOTE 1		$R_{\theta JA}$		92		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage		$C_J$		110		pF
Storage temperature			$T_{STG}$	-65		+150	$^\circ\text{C}$

**Note:** 1.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ )
DSK12	20	14	20	0.55	-55 to +125
DSK13	30	21	30		
DSK14	40	28	40		
DSK15	50	35	50	0.70	-55 to +150
DSK16	60	42	60		
DSK18	80	56	80	0.85	
DSK110	100	70	100		
DSK115	150	105	150	0.92	
DSK120	200	140	200		

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

\*4 Maximum forward voltage@ $I_F=1.0\text{A}$

### Rating and characteristic curves (DSK12 THRU DSK120)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

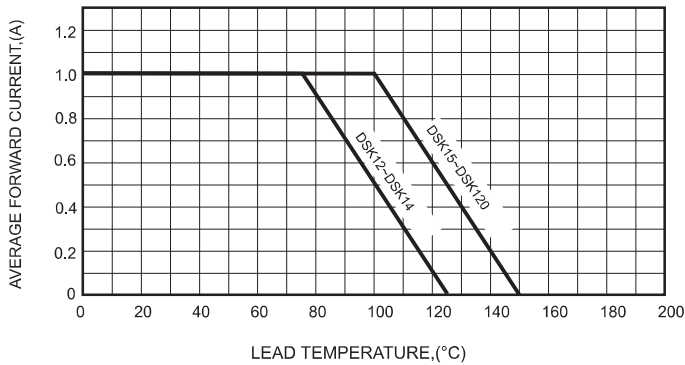


FIG.2-TYPICAL FORWARD CHARACTERISTICS

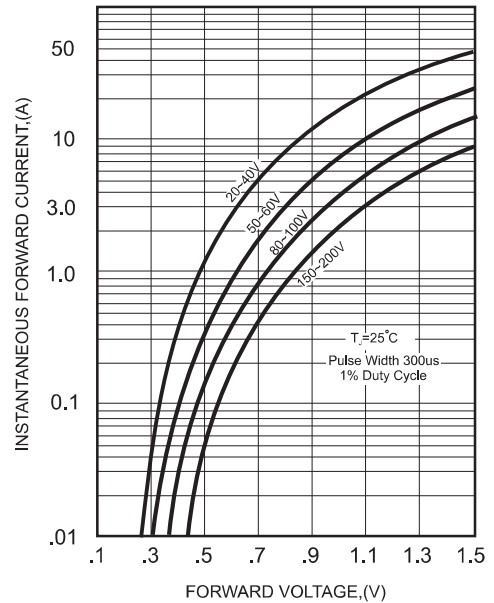


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

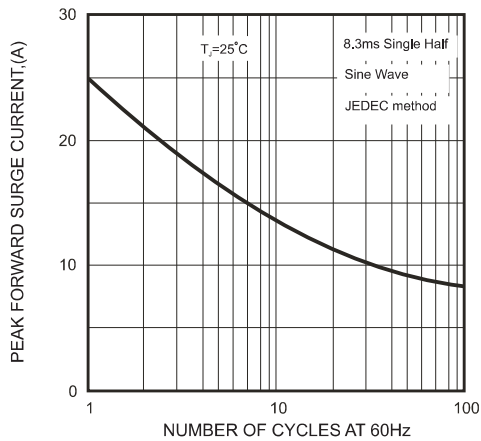


FIG.4-TYPICAL JUNCTION CAPACITANCE

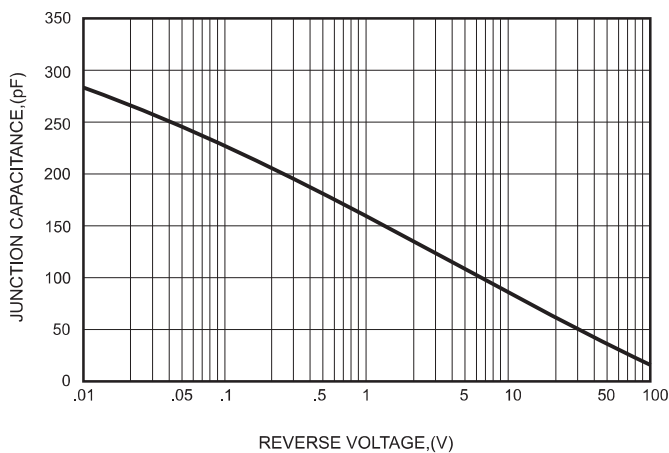
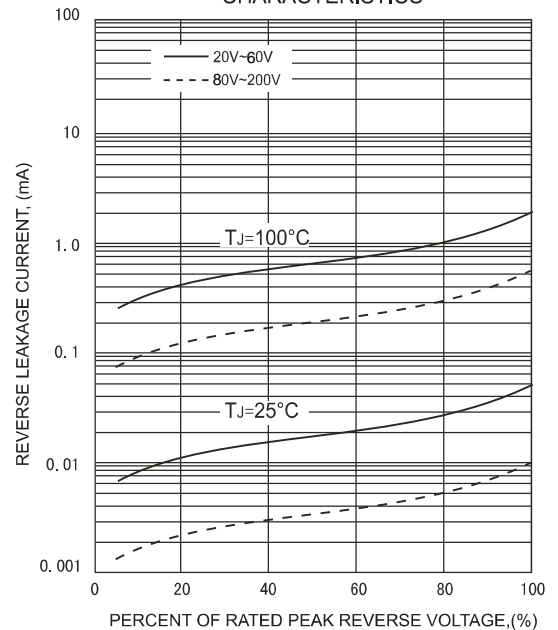
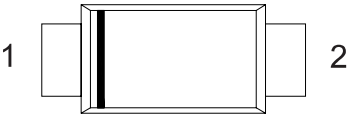



FIG.5 - TYPICAL REVERSE CHARACTERISTICS



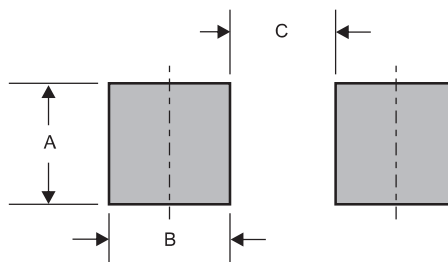
### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code
DSK12	12
DSK13	13
DSK14	14
DSK15	15
DSK16	16
DSK18	18
DSK110	10
DSK115	115
DSK120	120

### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)